

■ Application

Control equipment controlling heat excessively generated within the chamber in the semiconductor manufacturing process, and maintaining temperature by selecting from low to high temperature.

■ Applied fields

Etching, CVD

■ General Features

- ▶ Heat energy storage system
- ▶ Dynamic temperature coordination
- ▶ Energy savings
- ▶ Long MTBF
- ▶ Multi channel is used with one refrigeration system
- ▶ Quick response time, minimum variation
- ▶ Small sized footprint

■ Utility Requirements

Item	Specification
Dimension	580(W)×950(D)×1690(H)
Temperature Range	1CH : 20°C ~ +80°C / 2CH : 20°C ~ +80°C 3CH : -10°C ~ +80°C / 4CH : -10°C ~ +80°C
Cooling Capacity	1CH : 3000 watts at 50 °C / 2CH : 3000 watts at 50 °C 3CH : 4000 watts at 20 °C / 4CH : 4000 watts at 20 °C
Coolant Flow Rate	30LPM, 0.2~0.8Mpa (flux / pressure control)
Coolant Type	FC-3283
Electrical Spec	208V, 3P, 4W, 75A (normal 40A)
Temperature Accuracy	±0.1 °C

